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SIST EN 16602-70-38:2019

Zagotavljanje varnih proizvodov v vesoljski tehniki - Visoko zanesljivo spajkanje za površinsko namestitev, mešano tehnologijo in ročno pritrjene električne priključke

iTeh STANDARD PREVIEW

Space product assurance - High-reliability soldering for surface mount, mixed technology and hand-mounted electrical connections

Raumfahrtproduktsicherung - Hochzuverlässige Montage von Oberflächen-Befestigungen und Durchgangslochverbindungen

Assurance produit des projets spatiaux - Soudure haute fiabilité pour les connexions électriques à montage en surface, à technologie combinée et montées à la main

Ta slovenski standard je istoveten z: EN 16602-70-61:2022

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surface mount, mixed technology and hand-mounted
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Raumfahrtproduktsicherung - Hochzuverlässige
Montage von Oberflächen-Befestigungen und
Durchgangslochverbindungen

This European Standard was approved by CEN on 29 August 2022.

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This European Standard exists in three official versions (English, French, German). A version in any other language made by translation under the responsibility of a CEN and CENELEC member into its own language and notified to the CEN-CENELEC Management Centre has the same status as the official versions.

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Rue de la Science 23, B-1040 Brussels**

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European Foreword

This document (EN 16602-70-61:2022) has been prepared by Technical Committee CEN/CLC/JTC 5 "Space", the secretariat of which is held by DIN (Germany).

This document (EN 16602-70-61:2022) originates from ECSS-Q-ST-70-61C.

This European Standard shall be given the status of a national standard, either by publication of an identical text or by endorsement, at the latest by May 2023, and conflicting national standards shall be withdrawn at the latest by May 2023.

Attention is drawn to the possibility that some of the elements of this document may be the subject of patent rights. CEN [and/or CENELEC] shall not be held responsible for identifying any or all such patent rights.

This document supersedes EN 16602-70-38:2019; EN 16602-70-07:2014; EN 16602-70-08:2015.

This new ECSS Standard (ECSS-Q-ST-70-61C) was created by merging and updating the content of the following three standards:

- ECSS-Q-ST-70-07C "Verification and approval of automatic machine wave soldering"
- ECSS-Q-ST-70-08C "Manual soldering of high-reliability electrical connections"
- ECSS-Q-ST-70-38C, Rev.12 "High-reliability soldering for surface-mount and mixed technology"

The intention of this completely new standard was to optimize the structure of the document, following the chronological order of assembly processes and introducing criterion for new technologies that were not covered by the three standards now superseded by this new standard.

This document has been prepared under a standardization request given to CEN by the European Commission and the European Free Trade Association.

This document has been developed to cover specifically space systems and will therefore have precedence over any EN covering the same scope but with a wider do-main of applicability (e.g.: aerospace).

According to the CEN-CENELEC Internal Regulations, the national standards organizations of the following countries are bound to implement this European Standard: Austria, Belgium, Bulgaria, Croatia, Cyprus, Czech Republic, Denmark, Estonia, Finland, Former Yugoslav Republic of Macedonia, France, Germany, Greece, Hungary, Iceland, Ireland, Italy, Latvia, Lithuania, Luxembourg, Malta, Netherlands, Norway, Poland, Portugal, Romania, Serbia, Slovakia, Slovenia, Spain, Sweden, Switzerland, Türkiye and the United Kingdom.